

CFW  
TSMC-00-101C

April 30, 2004



To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/812,734 03/30/04

Shau-Lin Shue et al.

METHOD FOR FORMING A SELF-PASSIVATED  
COPPER INTERCONNECT STRUCTURE

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450 on May 4, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 5/4/04

TSMC-00-101C

U.S. Patent 5,913,147 to Dubin et al., "Method for Fabricating Copper-Aluminum Metallization," discloses a layer over a Cu alloy plug.

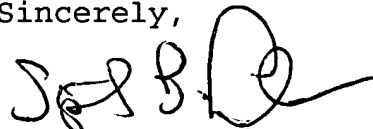
U.S. Patent 5,728,629 to Mizuno et al., "Process for Preventing Deposition on Inner Surfaces of CVD Reactor," discloses a passivation process.

U.S. Patent 5,714,418 to Bai et al., "Diffusion Barrier for Electrical Interconnects in an Integrated Circuit," discloses a Cu interconnect.

U.S. Patent 5,391,517 to Gelatos et al., "Process for Forming Copper Interconnect Structure," discloses a Cu interconnect.

U.S. Patent 6,046,108 to Liu et al., "Method for Selective Growth of  $\text{Cu}_3\text{Ge}$  or  $\text{Cu}_5\text{Si}$  for Passivation of Damascene Copper Structures and Device Manufactured Thereby," discloses a layer over a Cu plug.

Sincerely,

A handwritten signature in black ink, appearing to read "Stephen B. Ackerman". The signature is stylized with a large, looped "S" and a long, sweeping horizontal stroke at the end.

Stephen B. Ackerman,  
Reg. No. 37761

Form PTO-1449

# INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

MAY 06 2004

Docket Number (Optional)

TSMC-00-101C

Application Number

10/812,734

Applicant

Shau-Lin Shue et al.

Filing Date

03/30/04

Drawn by Unit

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	59131476	15/99	Dubin et al.	438	687	1/21/97
	57286293	17/98	Mizuno et al.	438	680	9/23/94
	57144182	3/98	Bai et al.	438	627	11/8/95
	53915172	21/95	Gelatos et al.	437	190	9/13/93
	60461084	4/00	Lin et al.	438	687	6/25/99

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Portmox Pages, Etc.)


EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.